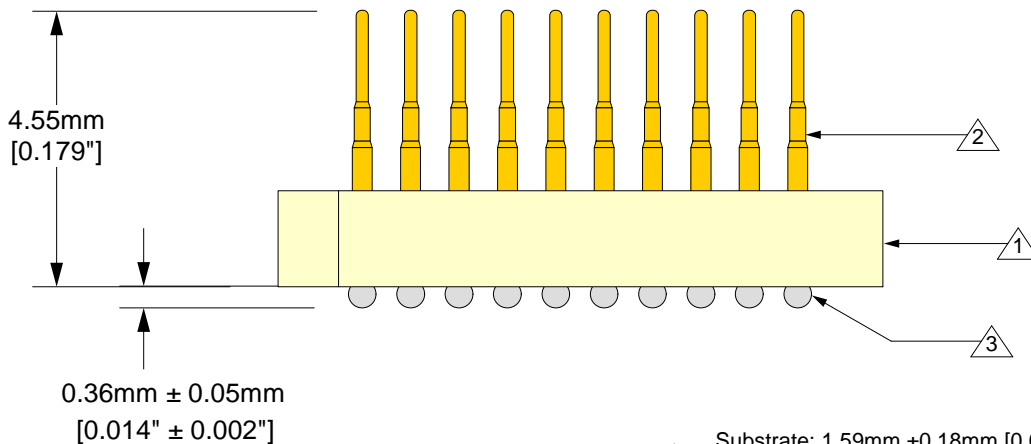


Top View




Side View

- △1 Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"]
FR4/G10 or equivalent high temp material;
Non-clad
- △2 Pins: material- Brass Alloy 360 1/2 hard; finish-
0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).
- △3 Solder Balls: Sn63Pb37

Description: Giga-snaP BGA SMT Foot

100 position terminal pins (0.8mm centers, 10x10 array) to SMT solder balls (BGA type). Pin assignment 1:1.

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA100C-B-61 Drawing		Status: Released	Scale: 8:1	Rev: B
 <p>© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: A. Evans		Date: 06/01/09	
	File: SF-BGA100C-B-61 Dwg.mcd		Modified: 07/01/14	